

**System and Method
for Cooling Electronic components**

Abstract

5 A system and method for cooling electronic components. The system includes a surface. One or more electronic components are coupled to the surface, the one or more electronic components including an integrated circuit in contact with a heat sink. A blower is coupled to the surface, the blower having a first port, a second port, and an impeller that rotates around an axis.
10 The blower is oriented such that the axis is perpendicular to the surface and non-intersecting with the heat sink, wherein the blower moves air across the heat sink.

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